Special Issue

Flexible Intelligent Sensors: Design, Fabrication and Applications

Message from the Guest Editor

Flexible intelligent sensors gain momentum when acquiring, storing, and calculating information compared to traditional sensors or transistors. For applications related to the realization of precise tactile sensation on humanoid robots or health monitoring using skin or organ tissue, flexible intelligent sensors have the power to significantly enhance smart sensing functions and reduce the dimension of devices within a limited space or surface. Recent developments in novel sensing mechanisms, advanced materials, smart algorithms, and special fabrication technology have further boosted the advancement of flexible intelligent sensors. Furthermore, these sensors will be smarter, more integrated, and exhibit a higher performance in various contexts, such as disease diagnosis, robot precise manipulation, and human/machine long-term health monitoring. One common aim of this Special Issue is to gather innovative and high-impact works related to flexible intelligent sensors, with a particular focus on technical advancements and recent developments. We welcome scholars to contribute research papers, review articles, and perspectives.

Guest Editor

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